| | Material Composit © Copyright 2005. IPC, I nternational and Pan-Am | Bannockb | urn, Illinois. A | ll rights reserved tions. | under both | This docume level parts, t | ent is a declarat he declaration e | on of the su | ibstances v s all lower | vithin the manufact level materials for | urer listed which the i | item. Note: nanufactur | if the item is an as er has engineering | ssembly with low responsibility. | |
|--|---|-------------------|---------------------------|----------------------------|------------|---|---------------------------------------|---------------------------------|----------------------------|--|---------------------------------|---------------------------|--|----------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute | | | | * | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information | | | | | | | | | |
| Supplier Informati | ion | | | | | | | | | | | | | | |
| Company name* Company unio | | | | que ID Uni | | | Unique ID Authority | | | Respon | Response Date* | | | | |
| nsemi | | | | | | | | | | | 2023-00 | 2023-06-08 | | | |
| Contact Name | | | Title - Contact | | |] | Phone - Contact* | | | Email - | Email - Contact* | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | | NA | | | Produ | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* | | | Title - Representative | | |] | Phone - Representative* | | | Email - | Email - Representative* | | | | |
| Product-Env-Stewards | | | Product Envir | oduct Enviro Compliance NA | | | | Product-Env-Stewards@onsemi.com | | | | | | | |
| Requester Ite | Requester Item Number Mfr Item | | n Number Mfr Item Name | | | Effective Date | Version | ersion Manufacturing Site | | | Weight* | UOM | Unit Type | | |
| | | AR01350 A0-DPB | CS2M00SUE R | 1MP 1/3 CIS SO | , | | 2023-06-08 | | T. | A1 | | 200.0 | mg | Each | |
| Ianufacturing Pro | occess Information | l | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material Terminal Base A | | | lloy | J-STD-020 MSI | L Rating | Peak Proc | ess Body T | emperature | e Max Time at Pea | ık Tempera | ture Nun | nber of Reflow Cy | cles | | |
| SnAgCu CU Alloy 3 | | | 3 | | 260 | | С | 30 | seco | nds 3 | | | | | |
| omments | | | | | | | | | | | | | | | |
| FTENTION: MSL 3 I | Rated item requires Ba | ke and D | ry Pack (after | electrical test) | | | | | | | | | | | |
| or more information r | egarding material com | position | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed |
|--|--|--|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | nium (Cr6+), Polybro | ominated Biphenyls (PBB), Polybron | dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the |
| Supplier Digital Signature Ra | stislav Drska | Le | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|---------------------------|--------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Die | 32.4 | mg | | Misc. | proprietary data | | 0.1231 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 31.9561 | mg |
| | | | Supplier | Aluminum (Al) | 7429-90-5 | | 0.3208 | mg |
| Die Attach | 2.8 | mg | Supplier | Bisphenol A_Epichlorohydrin Polymer | 25068-38-6 | | 1.05 | mg |
| | | | Supplier | Ethylene Glycol | 107-21-1 | | 0.028 | mg |
| | | | Supplier | Sulfonium (Thiodi-4,1-phenylene) | 89452-37-9 | | 0.084 | mg |
| | | | Supplier | Modified Silicon Dioxide (SiO2) | 67762-90-7 | | 0.588 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | | 1.05 | mg |
| Imaging Lens | 28.48 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 1.4989 | mg |
| | | | Supplier | Sodium Monoxide (Na2O) | 1313-59-3 | | 1.4989 | mg |
| | | | Supplier | Zinc Monoxide (ZnO) | 1314-13-2 | | 1.4989 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 0.1501 | mg |
| | | | Supplier | Aluminum Trioxide (Al2O3) | 1344-28-1 | | 1.4989 | mg |
| | | | Supplier | Potassium Monoxide (K2O) | 12136-45-7 | | 1.4989 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 20.8354 | mg |
| Lid Attach | 1.46 | mg | Supplier | 2-phenoxy ethyl acrylate | 48145-04-6 | | 0.657 | mg |
| | | | Supplier | Bisphenol A_Epichlorohydrin Polymer | 25068-38-6 | | 0.292 | mg |
| | | | Supplier | Epoxy Prepolymer | Proprietary Data | | 0.1825 | mg |
| | | | Supplier | Acrylate Oligomer | Proprietary Data | | 0.0073 | mg |
| | | | Supplier | Curative | Proprietary Data | | 0.0292 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | | 0.292 | mg |
| Iold Compound-Black | 65.6 | mg | | Phenolic Resin | proprietary data | | 9.84 | mg |
| | | | Supplier | Oxirane | 39817-09-9 | | 9.84 | mg |
| | | | Supplier | 1,4-Bis(2,3-epoxypropoxy)butane | 2425-79-8 | | 1.968 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.656 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 41.984 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 1.312 | mg |
| older Ball | 29.5 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.885 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 28.4675 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.1475 | mg |
| Substrate and Solder Mask | 39.48 | mg | Supplier | Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane | 105391-33-1 | | 0.4422 | mg |

| | | | Supplier | Fiber Glass (SiO2) | 65997-17-3 | 5.1166 | mg |
|----------------|------|----|----------|--|------------------|---------|----|
| | | | Supplier | Zinc (Zn) | 7440-66-6 | 0.0592 | mg |
| | | | Supplier | Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2) | 14807-96-6 | 0.9199 | mg |
| | | | Supplier | Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer | 25722-66-1 | 0.4422 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | 0.229 | mg |
| | | | Supplier | Chromium (Cr) | 7440-47-3 | 0.0039 | mg |
| | | | Supplier | Acetophenone Derivative | Proprietary Data | 1.3779 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | 0.229 | mg |
| | | | Supplier | 2,4-Diethyl-9H-thioxanthen-9-one (DETX) | 82799-44-8 | 0.229 | mg |
| | | | Supplier | Aluminum Hydroxide (Al(OH)3) | 21645-51-2 | 4.7376 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | 0.5567 | mg |
| | | | Supplier | Gold (Au) | 7440-57-5 | 0.0197 | mg |
| | | | Supplier | Solvent Naphtha (Solvent oil) | 64742-94-5 | 2.7597 | mg |
| | | | Supplier | Formaldehyde Polymer | 9003-36-5 | 0.4422 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | 14.7892 | mg |
| | | | Supplier | Barium Sulfate (BaSO4) | 7727-43-7 | 7.1261 | mg |
| Wire Bond - Au | 0.28 | mg | Supplier | Gold (Au) | 7440-57-5 | 0.28 | mg |